

FIG. 1A (Prior Art)

TITLE: VIA PLACEMENT FOR LAYER TRANSITIONS IN FLEXIBLE CIRCUITS WITH HIGH
DENSITY BALL GRID ARRAYS
INVENTOR(S): Steven Rosenau, Ershad Ali, Jonathan Simon, Brian Lem ff, Lisa Ann Windov r
Attorney Dock t #: AGLT-10021114-1

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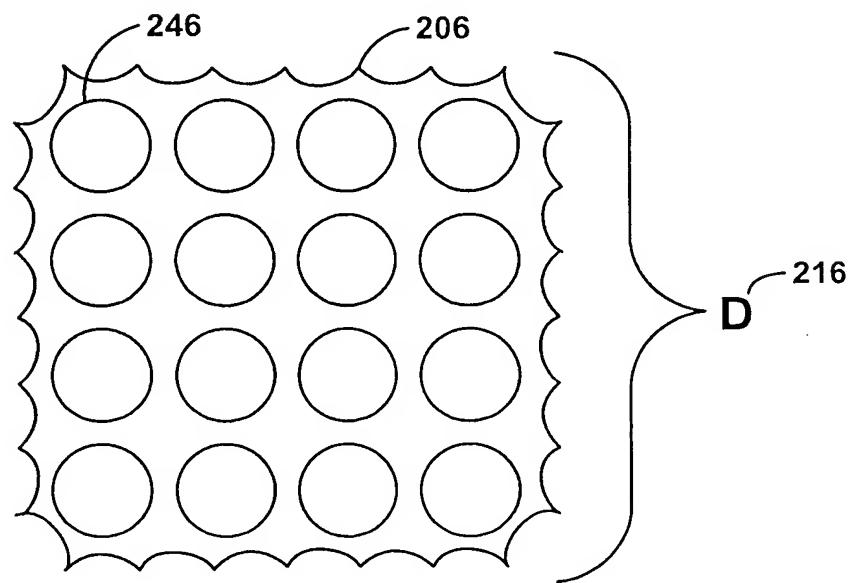


FIG. 1B (Prior Art)

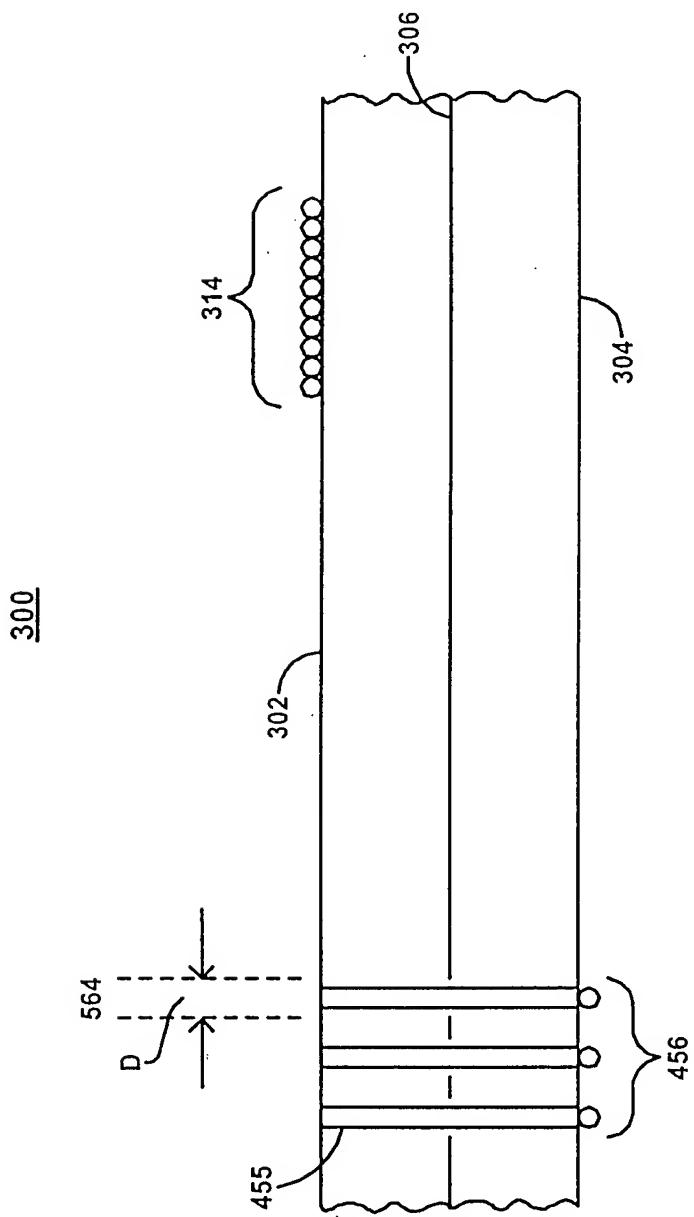


FIG. 2

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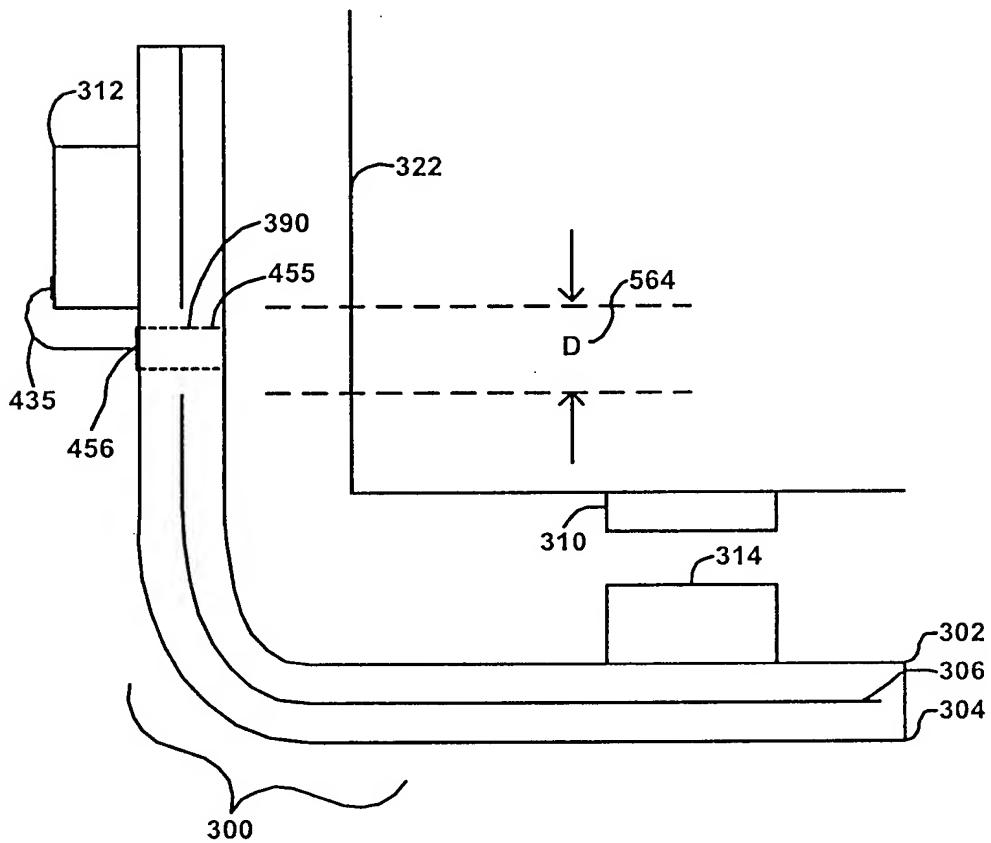


FIG. 3

TITLE: VIA PLACEMENT FOR LAYER TRANSITIONS IN FLEXIBLE CIRCUITS WITH HIGH DENSITY BALL

GRID ARRAYS

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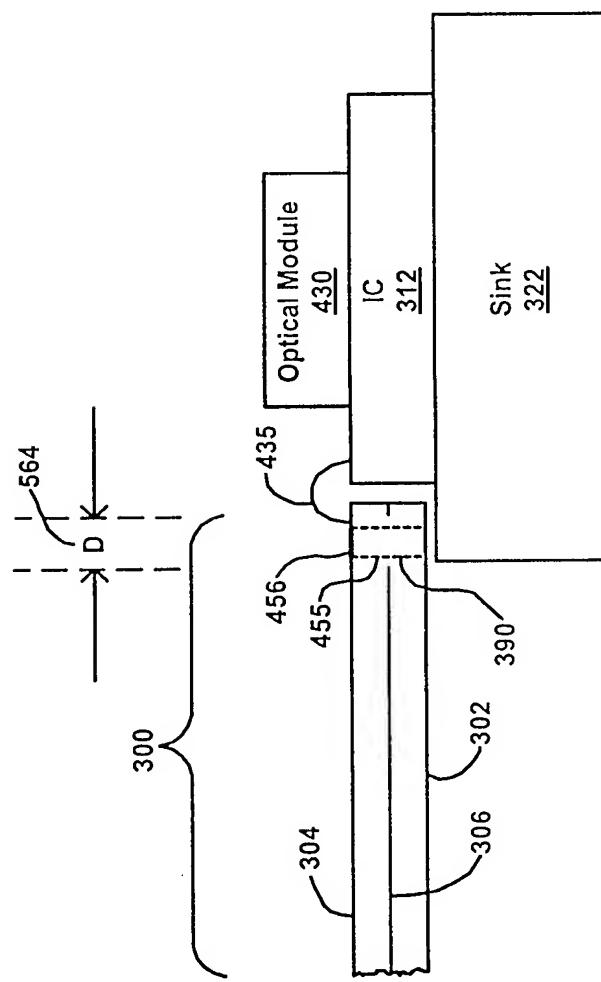


FIG. 4A

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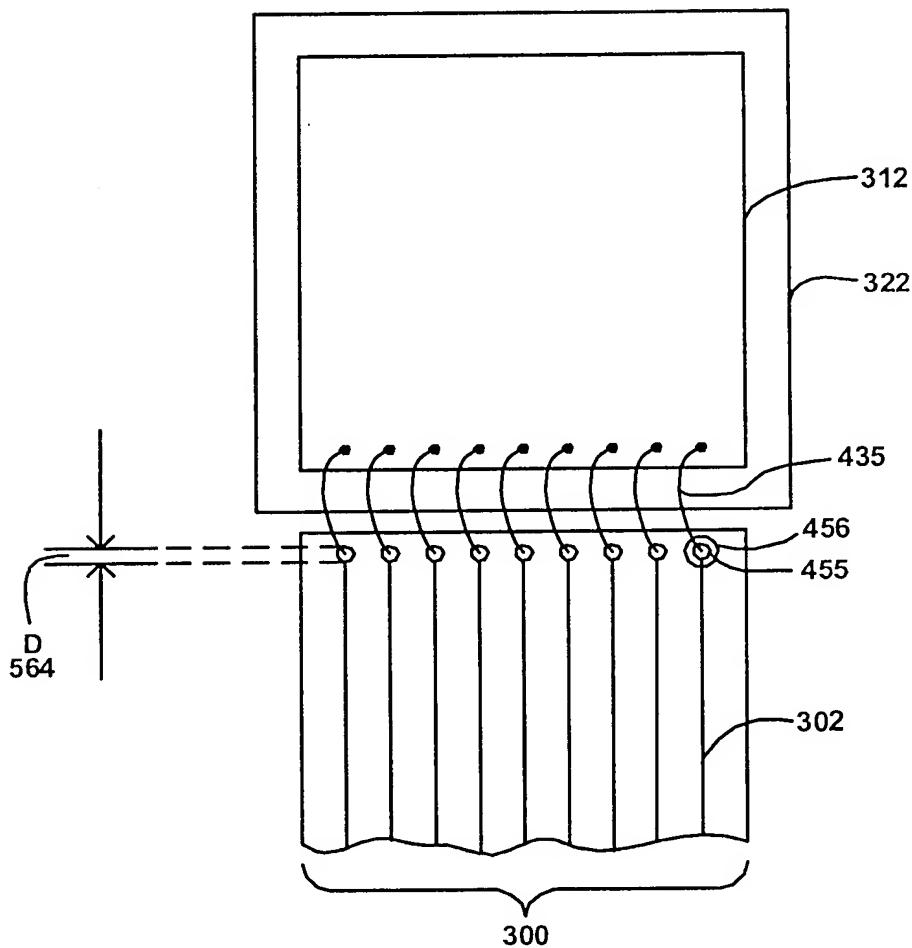


FIG. 4B

TITLE: VIA PLACEMENT FOR LAYER TRANSITIONS IN FLEXIBLE CIRCUITS WITH HIGH DENSITY BALL GRID ARRAYS

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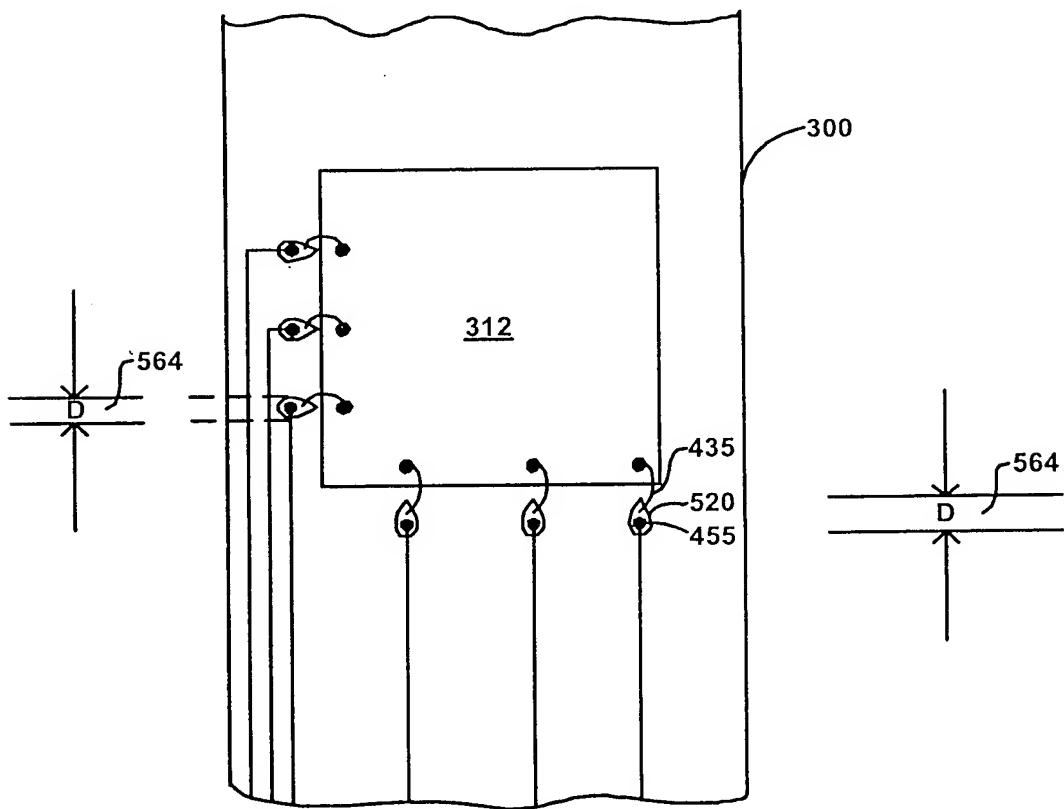


FIG. 5A

TITLE: VIA PLACEMENT FOR LAYER TRANSITIONS IN FLEXIBLE CIRCUITS WITH HIGH DENSITY BALL GRID ARRAYS

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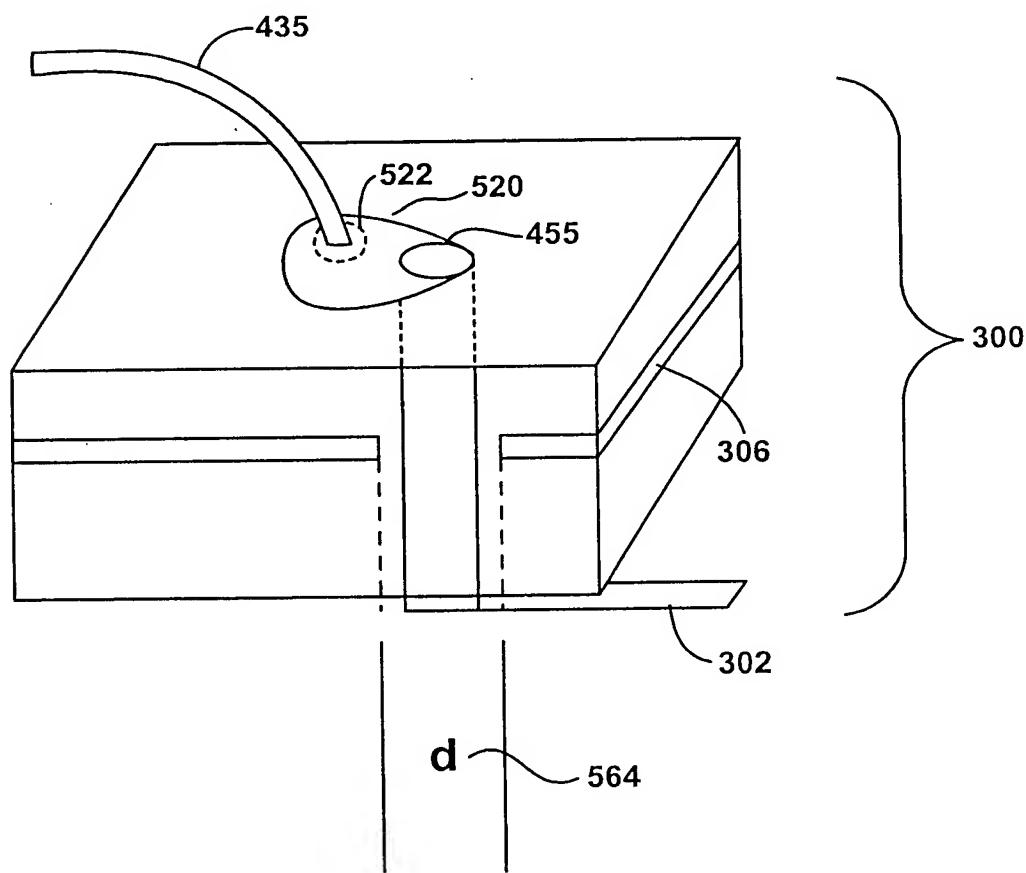


FIG. 5B

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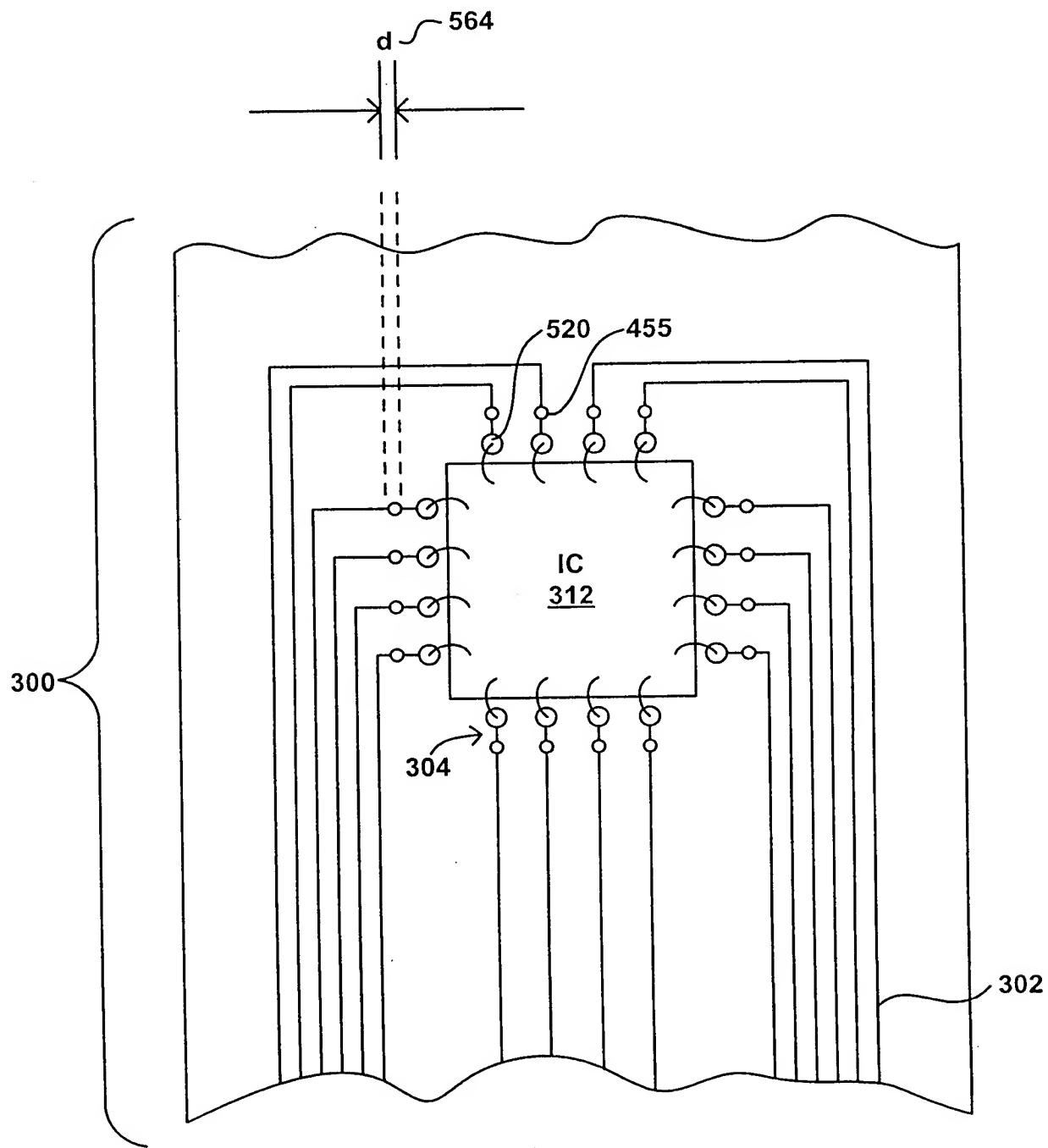


FIG. 5C